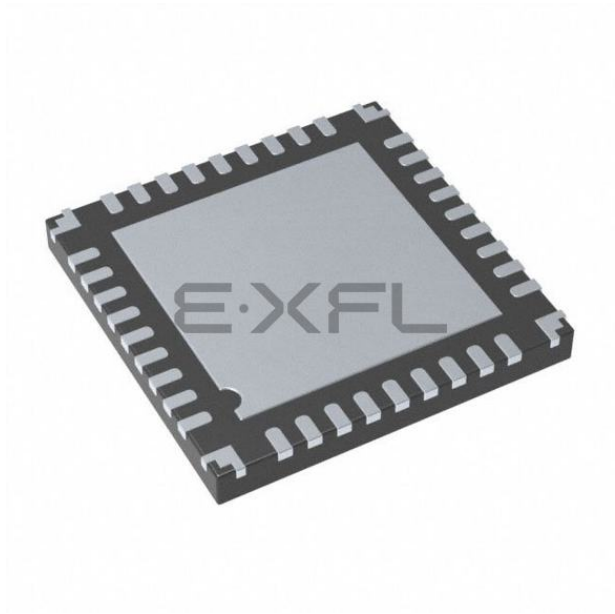
Microchip Technology - DSPIC33EV32GM103-I/M5 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-UFQFN Exposed Pad
Supplier Device Package	36-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev32gm103-i-m5

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not exceeding 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3 or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site (www.microchip.com).

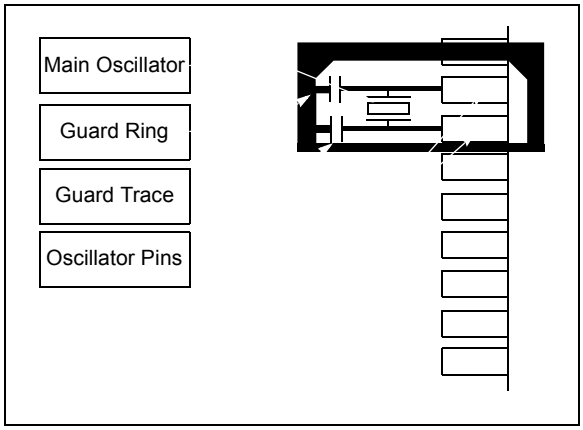
- *"Using MPLAB® ICD 3"* (poster) (DS51765)
- *"MPLAB® ICD 3 Design Advisory"* (DS51764)
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* (DS51616)
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) (DS51749)

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For more information, see **Section 9.0 "Oscillator Configuration"**.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed as shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 5 MHz < F_{IN} < 13.6 MHz to comply with device PLL start-up conditions. This intends that, if the external oscillator frequency is outside this range, the application must start up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLFBD, to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source.

Note:	Clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

Alternatively, connect a 1k to 10k resistor between V_{SS} and unused pins, and drive the output to logic low.

TABLE 4-2: TIMERS REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																0000
PR1	0102	Period Register 1																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																0000
TMR3HLD	0108	Timer3 Holding Register (For 32-bit timer operations only)																0000
TMR3	010A	Timer3 Register																0000
PR2	010C	Period Register 2																FFFF
PR3	010E	Period Register 3																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR4	0114	Timer4 Register																0000
TMR5HLD	0116	Timer5 Holding Register (For 32-bit operations only)																0000
TMR5	0118	Timer5 Register																0000
PR4	011A	Period Register 4																FFFF
PR5	011C	Period Register 5																FFFF
T4CON	011E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T5CON	0120	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 11-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION)

Input Name(1)	Function Name	Register	Configuration Bits
External Interrupt 1	INT1	RPINR0	INT1R<7:0>
External Interrupt 2	INT2	RPINR1	INT2R<7:0>
Timer2 External Clock	T2CK	RPINR3	T2CKR<7:0>
Input Capture 1	IC1	RPINR7	IC1R<7:0>
Input Capture 2	IC2	RPINR7	IC2R<7:0>
Input Capture 3	IC3	RPINR8	IC3R<7:0>
Input Capture 4	IC4	RPINR8	IC4R<7:0>
Output Compare Fault A	OCFA	RPINR11	OCFAR<7:0>
PWM Fault 1	FLT1	RPINR12	FLT1R<7:0>
PWM Fault 2	FLT2	RPINR12	FLT2R<7:0>
UART1 Receive	U1RX	RPINR18	U1RXR<7:0>
UART2 Receive	U2RX	RPINR19	U2RXR<7:0>
SPI2 Data Input	SDI2	RPINR22	SDI2R<7:0>
SPI2 Clock Input	SCK2	RPINR22	SCK2R<7:0>
SPI2 Slave Select	$\overline{SS2}$	RPINR23	SS2R<7:0>
CAN1 Receive	C1RX	RPINR26	C1RXR<7:0>
PWM Sync Input 1	SYNCI1	RPINR37	SYNCI1R<7:0>
PWM Dead-Time Compensation 1	DTCMP1	RPINR38	DTCMP1R<7:0>
PWM Dead-Time Compensation 2	DTCMP2	RPINR39	DTCMP2R<7:0>
PWM Dead-Time Compensation 3	DTCMP3	RPINR39	DTCMP3R<7:0>
SENT1 Input	SENT1R	RPINR44	SENT1R<7:0>
SENT2 Input	SENT2R	RPINR45	SENT2R<7:0>

Note 1: Unless otherwise noted, all inputs use the Schmitt Trigger input buffers.

11.6 High-Voltage Detect (HVD)

dsPIC33EVXXXGM00X/10X devices contain High-Voltage Detection (HVD) which monitors the VCAP voltage. The HVD is used to monitor the VCAP supply voltage to ensure that an external connection does not raise the value above a safe level (~2.4V). If high core voltage is detected, all I/Os are disabled and put in a tri-state condition. The device remains in this I/O tri-state condition as long as the high-voltage condition is present.

11.7 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 30-10 under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes that the resulting current being injected into the device, that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name, from left-to-right. The left most function name takes precedence over any function to its right in the naming convention; for example, AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(VDD – 0.8), not VDD. This value is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specifications. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

   VOH = 4.4V at IOH = -8 mA and VDD = 5V

   The maximum output current sourced by any 8 mA I/O pin = 12 mA.

   LED source current, <12 mA, is technically permitted. For more information, refer to the VOH/IOH specifications in **Section 30.0 “Electrical Characteristics”**.

REGISTER 11-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC2R7	IC2R6	IC2R5	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC1R7	IC1R6	IC1R5	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **IC2R<7:0>:** Assign Input Capture 2 (IC2) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

bit 7-0 **IC1R<7:0>:** Assign Input Capture 1 (IC1) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 11-6: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OCFAR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **OCFAR<7:0>:** Assign Output Compare Fault A (OCFA) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 20-1: SENTxCON1: SENTx CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
SNTEN	—	SNTSIDL	—	RCVEN	TXM(1)	TXPOL(1)	CRCEN
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
PPP	SPCEN(2)	—	PS	—	NIBCNT2	NIBCNT1	NIBCNT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **SNTEN:** SENTx Enable bit
1 = SENTx is enabled
0 = SENTx is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SNTSIDL:** SENTx Stop in Idle Mode bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **Unimplemented:** Read as '0'

bit 11 **RCVEN:** SENTx Receive Enable bit
1 = SENTx operates as a receiver
0 = SENTx operates as a transmitter (sensor)

bit 10 **TXM:** SENTx Transmit Mode bit(1)
1 = SENTx transmits data frame only when triggered using the SYNCTXEN status bit
0 = SENTx transmits data frames continuously while SNTEN = 1

bit 9 **TXPOL:** SENTx Transmit Polarity bit(1)
1 = SENTx data output pin is low in the Idle state
0 = SENTx data output pin is high in the Idle state

bit 8 **CRCEN:** CRC Enable bit
Module in Receive Mode (RCVEN = 1):
1 = SENTx performs CRC verification on received data using the preferred J2716 method
0 = SENTx does not perform CRC verification on received data
Module in Transmit Mode (RCVEN = 1):
1 = SENTx automatically calculates CRC using the preferred J2716 method
0 = SENTx does not calculate CRC

bit 7 **PPP:** Pause Pulse Present bit
1 = SENTx is configured to transmit/receive SENT messages with pause pulse
0 = SENTx is configured to transmit/receive SENT messages without pause pulse

bit 6 **SPCEN:** Short PWM Code Enable bit(2)
1 = SPC control from external source is enabled
0 = SPC control from external source is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **PS:** SENTx Module Clock Prescaler (divider) bits
1 = Divide-by-4
0 = Divide-by-1

Note 1: This bit has no function in Receive mode (RCVEN = 1).
2: This bit has no function in Transmit mode (RCVEN = 0).

NOTES:

REGISTER 22-22: CxRXFUL1: CANx RECEIVE BUFFER FULL REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL<15:8>							
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL<7:0>							
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<15:0>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (cleared by user software)

REGISTER 22-23: CxRXFUL2: CANx RECEIVE BUFFER FULL REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL<31:24>							
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL<23:16>							
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<31:16>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (cleared by user software)

REGISTER 25-3: CM4CON: COMPARATOR 4 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R-0
CON	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1(2)	EVPOL0(2)	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator 4 Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 14 **COE:** Comparator 4 Output Enable bit
1 = Comparator output is present on the C4OUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator 4 Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-10 **Unimplemented:** Read as '0'

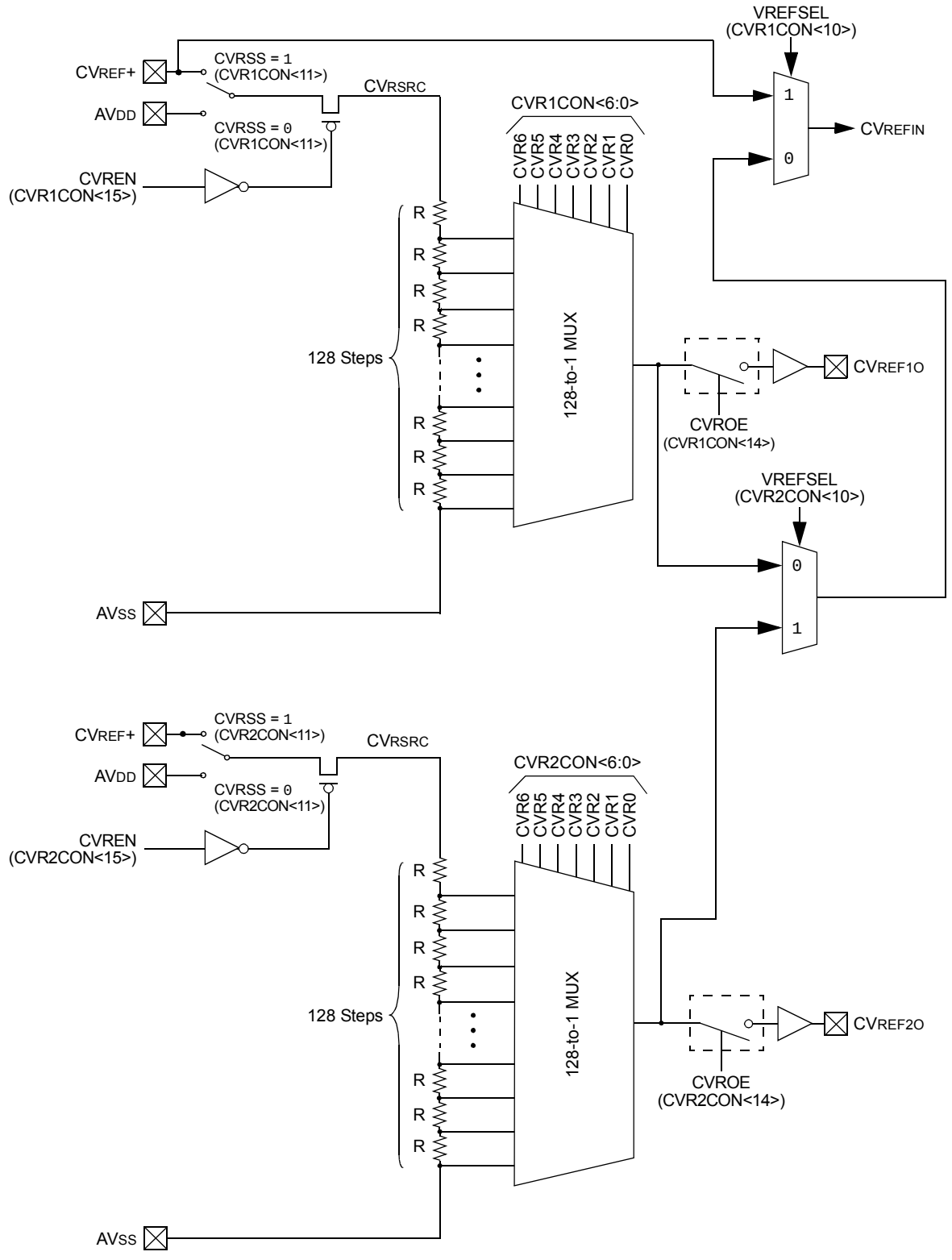
bit 9 **CEVT:** Comparator 4 Event bit
1 = Comparator event, according to EVPOL<1:0> settings, occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator 4 Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

2: After configuring the comparator, either for a high-to-low or low-to-high COUT transition (EVPOL<1:0> (CMxCON<7:6>) = 10 or 01), the comparator Event bit, CEVT (CMxCON<9>), and the Comparator Combined Interrupt Flag, CMPIF (IFS1<2>), must be cleared before enabling the Comparator Interrupt Enable bit, CMPIE (IEC1<2>).

FIGURE 26-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



Note 1: CVREF2O and CVROE (CVR2CON<14>) is not available on the 28-pin devices.

TABLE 30-34: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	$\overline{SDO2}$ Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-54: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or VBOR	—	Lesser of: VDD + 0.3 or 5.5	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	4.5	—	5.5	V	VREFH = AVDD, VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – VBORMIN	V	See **Note 1**
AD06a			0	—	0	V	VREFH = AVDD, VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	4.5	—	5.5	V	VREF = VREFH – VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current	— —	5 2	— —	mA mA	ADC operating in 10-bit mode (see **Note 1**) ADC operating in 12-bit mode (see **Note 1**)
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but is not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of the dsPIC33EVXXXGM00X/10X family electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EVXXXGM00X/10X family high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these, or any other conditions above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(2) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.0V
Maximum current out of V_{SS} pin ..... 350 mA
Maximum current into V_{DD} pin(3) ..... 350 mA
Maximum junction temperature ..... +155°C
Maximum current sunk by any I/O pin ..... 20 mA
Maximum current sourced by I/O pin ..... 18 mA
Maximum current sunk by all ports combined ..... 200 mA
Maximum current sourced by all ports combined(3) ..... 200 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

FIGURE 32-5: TYPICAL IDD vs. VDD (EC MODE, 60 MIPS)

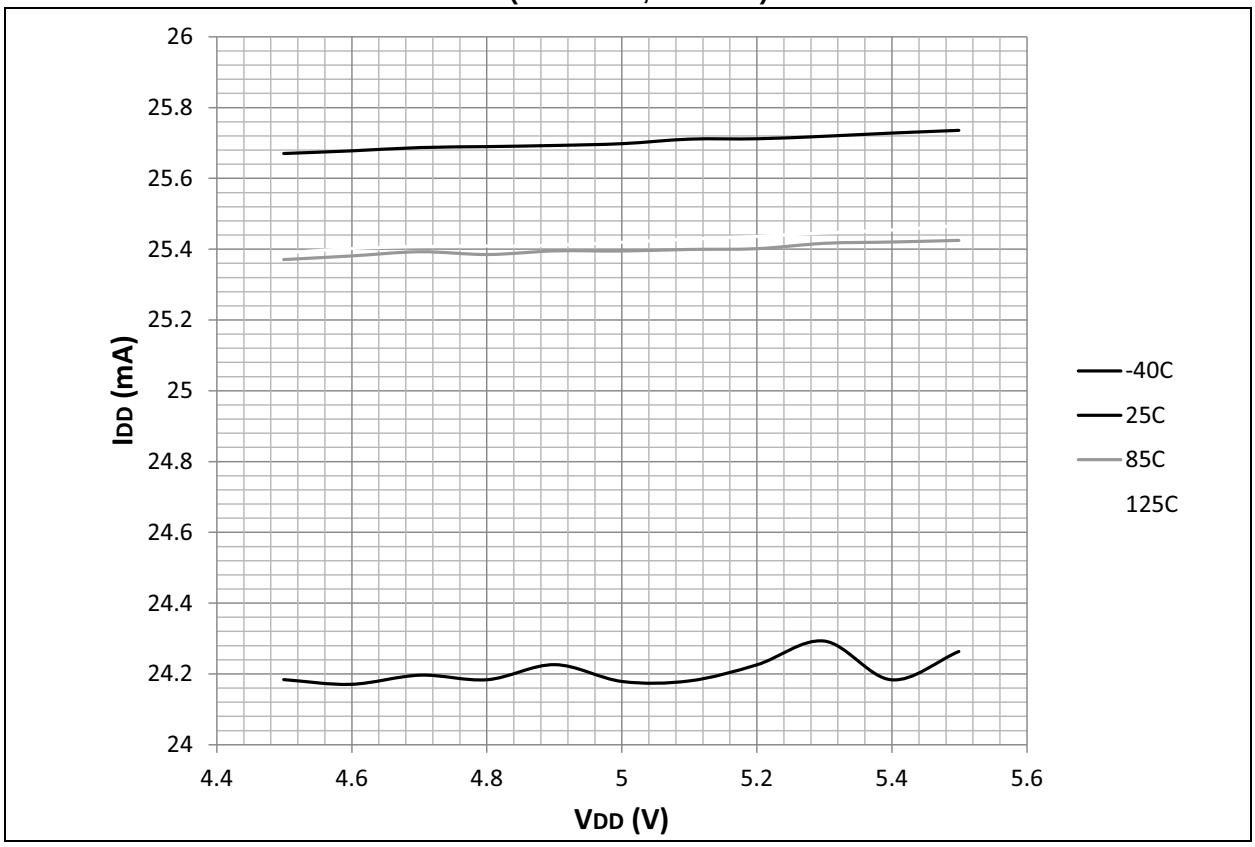


FIGURE 32-6: TYPICAL IDD vs. VDD (EC MODE, 70 MIPS)

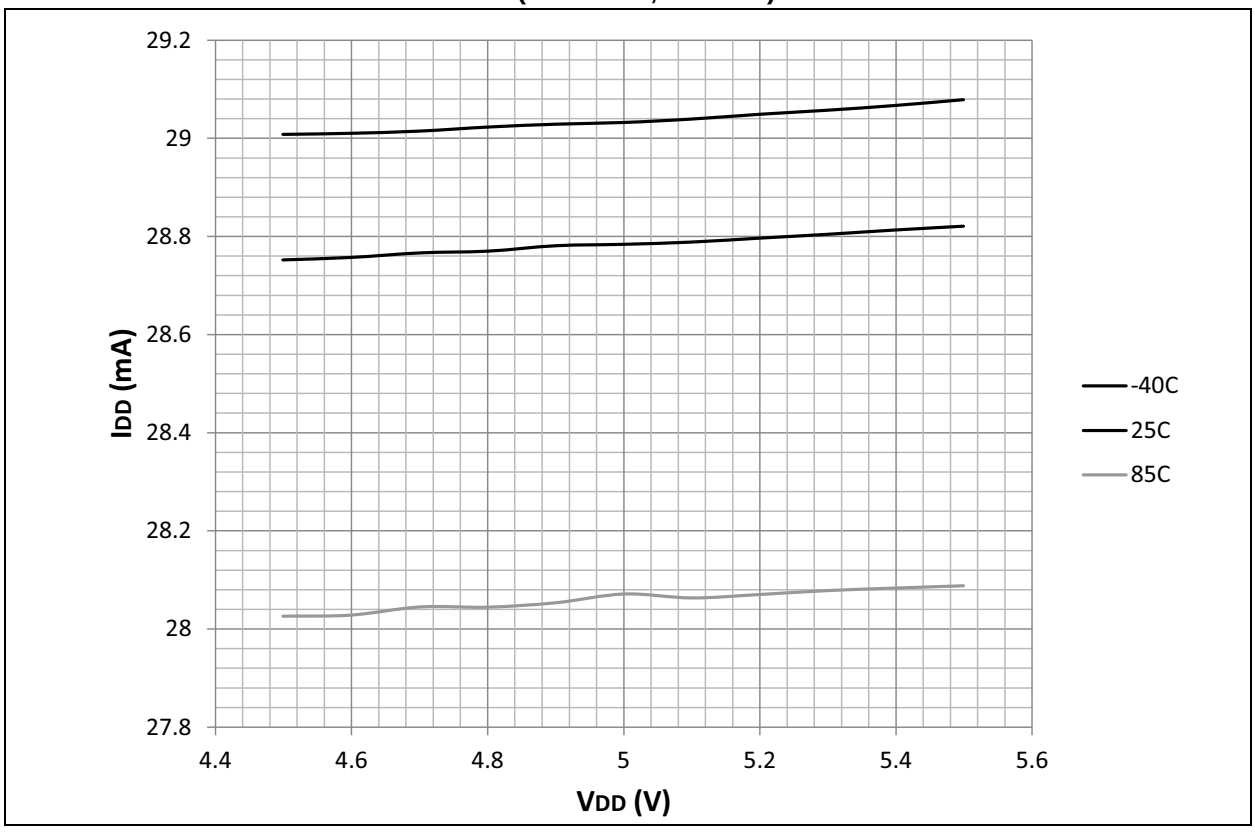
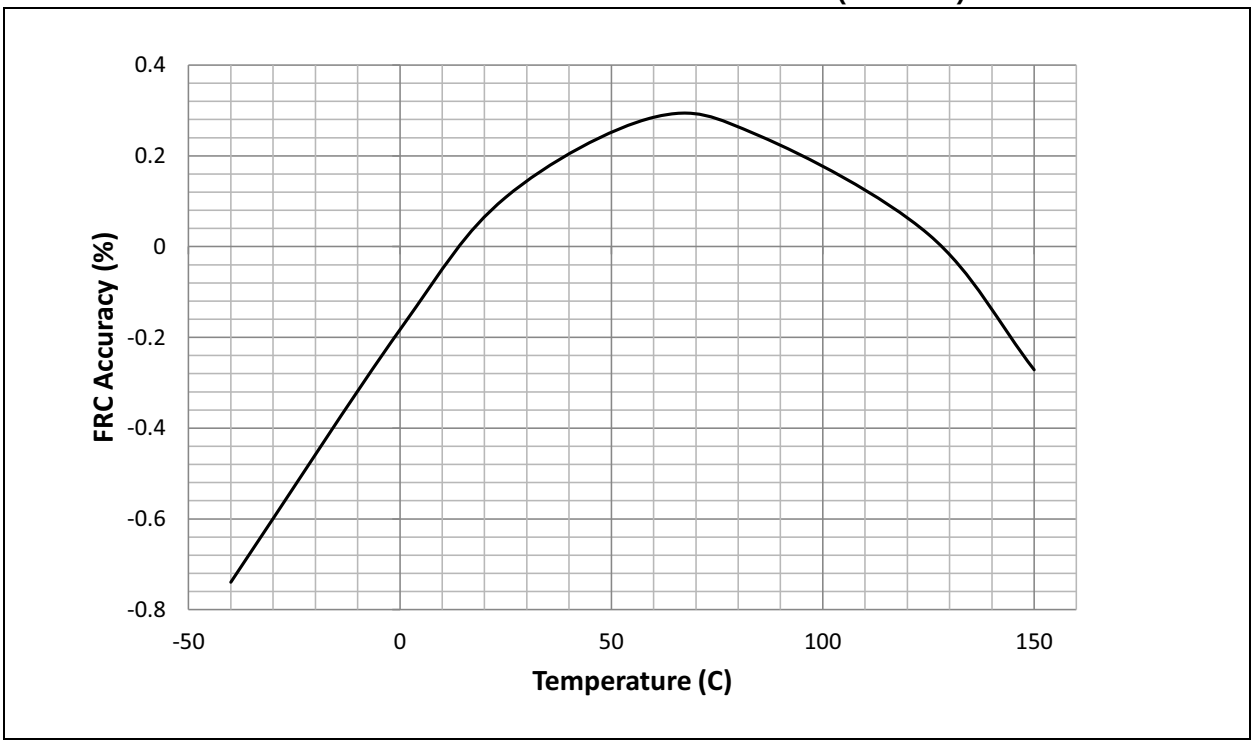
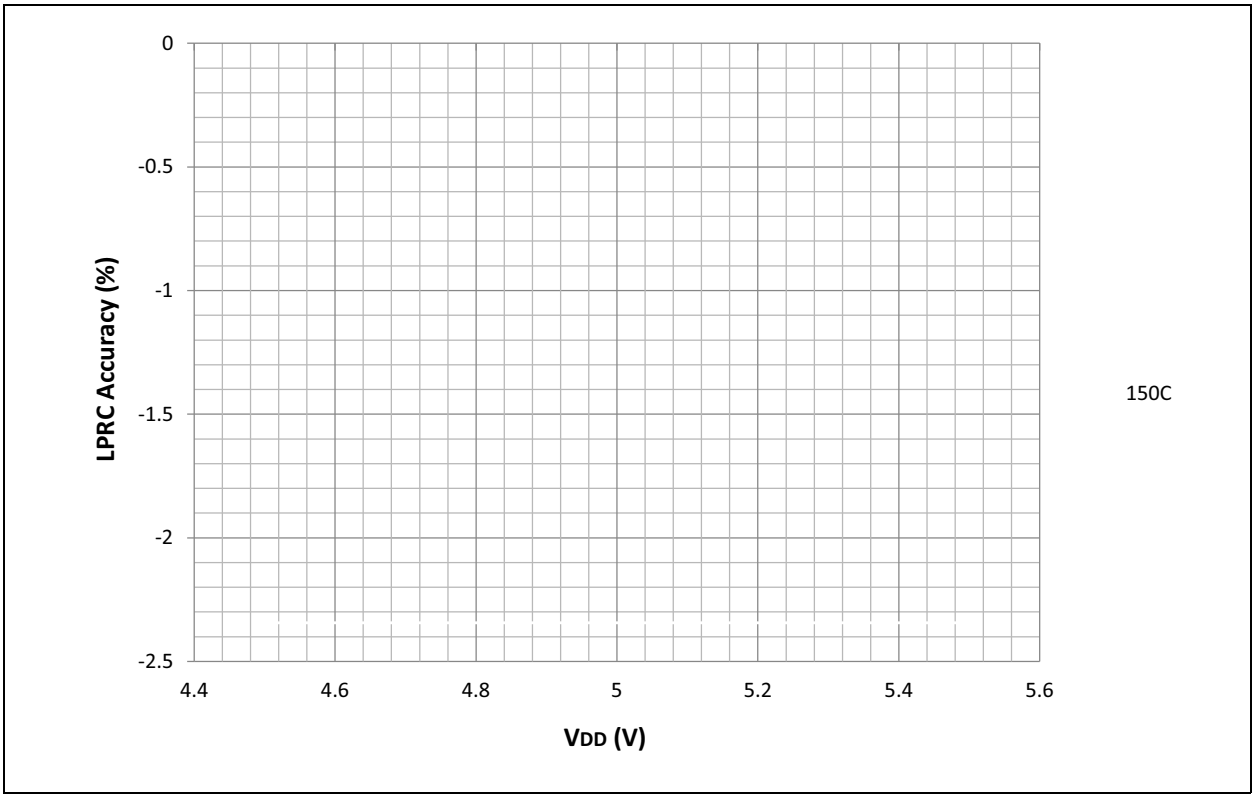


FIGURE 33-17: TYPICAL FRC ACCURACY vs. TEMPERATURE (5.5V VDD)



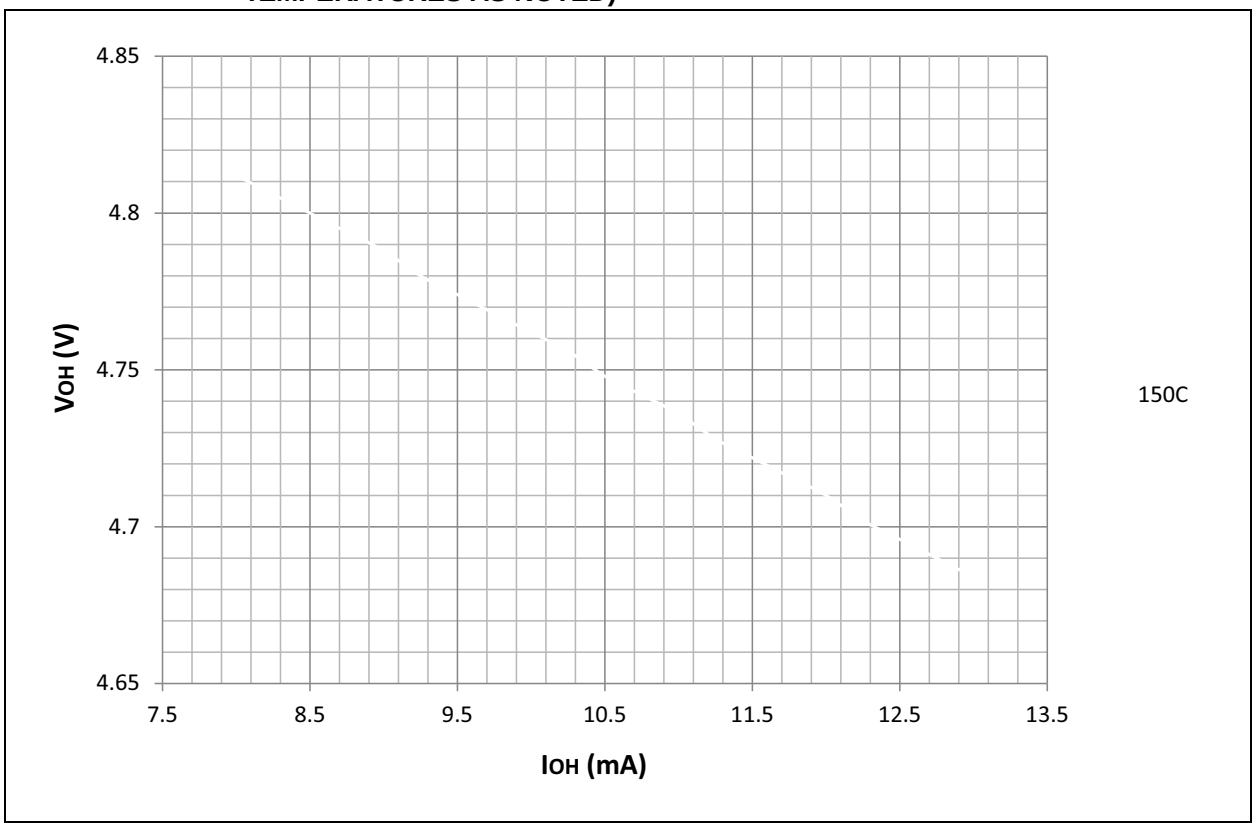
33.6 LPRC

FIGURE 33-18: TYPICAL LPRC ACCURACY vs. VDD



33.10 Voltage Output Low (V_{OL}) – Voltage Output High (V_{OH})

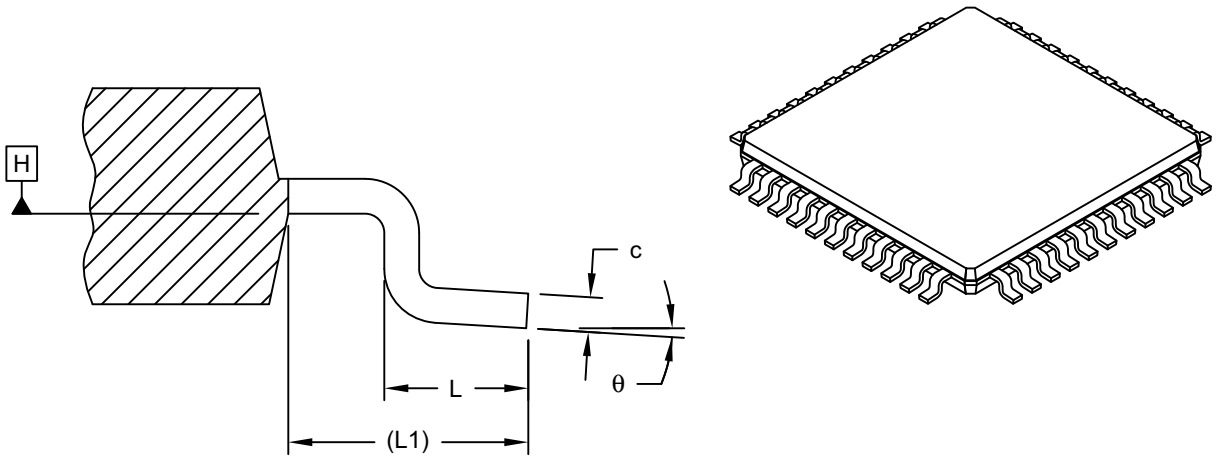
FIGURE 33-26: TYPICAL V_{OH} 8x DRIVER PINS vs. I_{OH} (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)



NOTES:

44-Lead Plastic Thin Quad Flatpack (PT) - 10x10x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	-	-	1.20
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Width	E		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Width	b	0.30	0.37	0.45
Lead Thickness	c	0.09	-	0.20
Lead Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	θ	0°	3.5°	7°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Exact shape of each corner is optional.
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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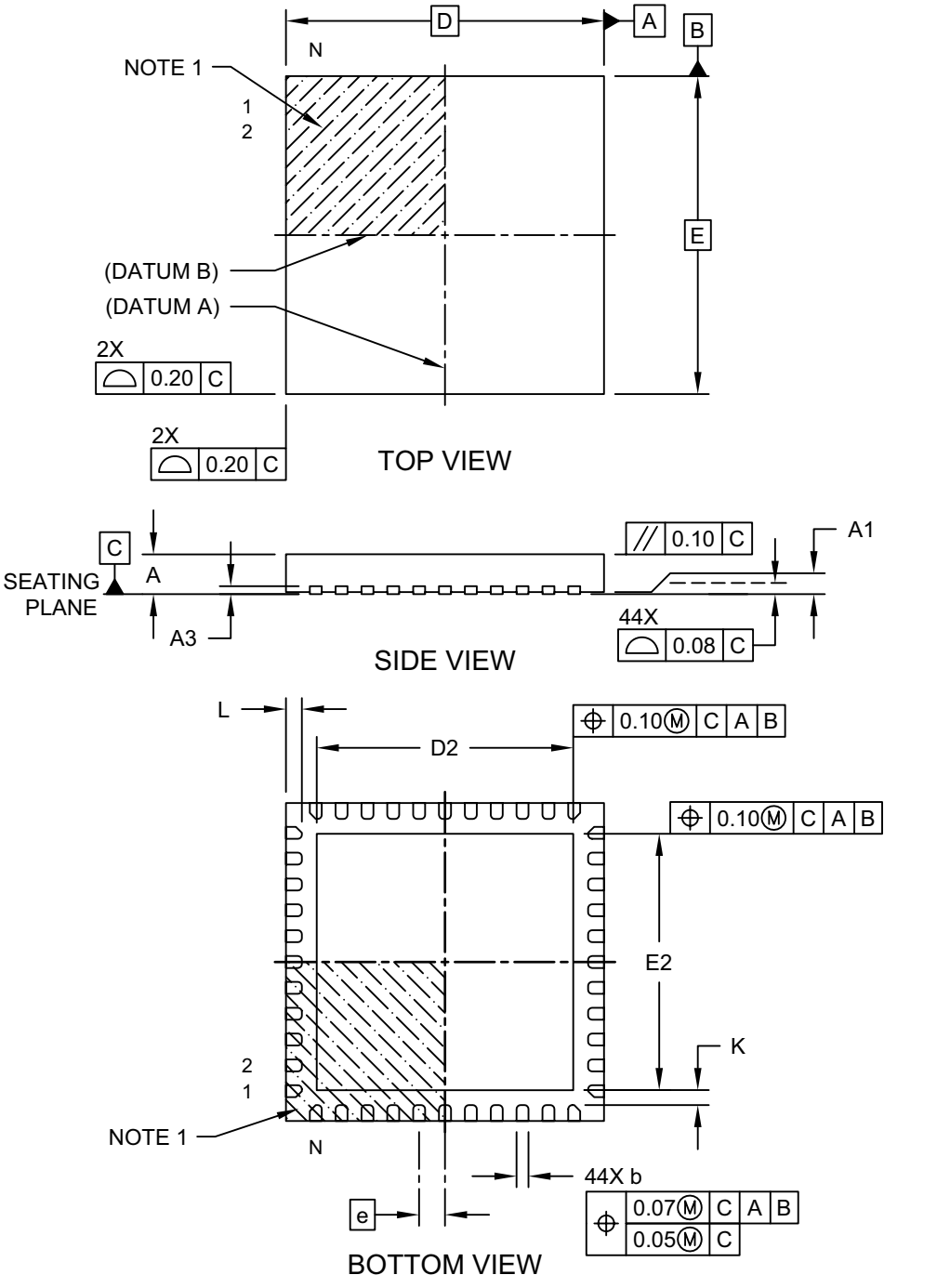
44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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